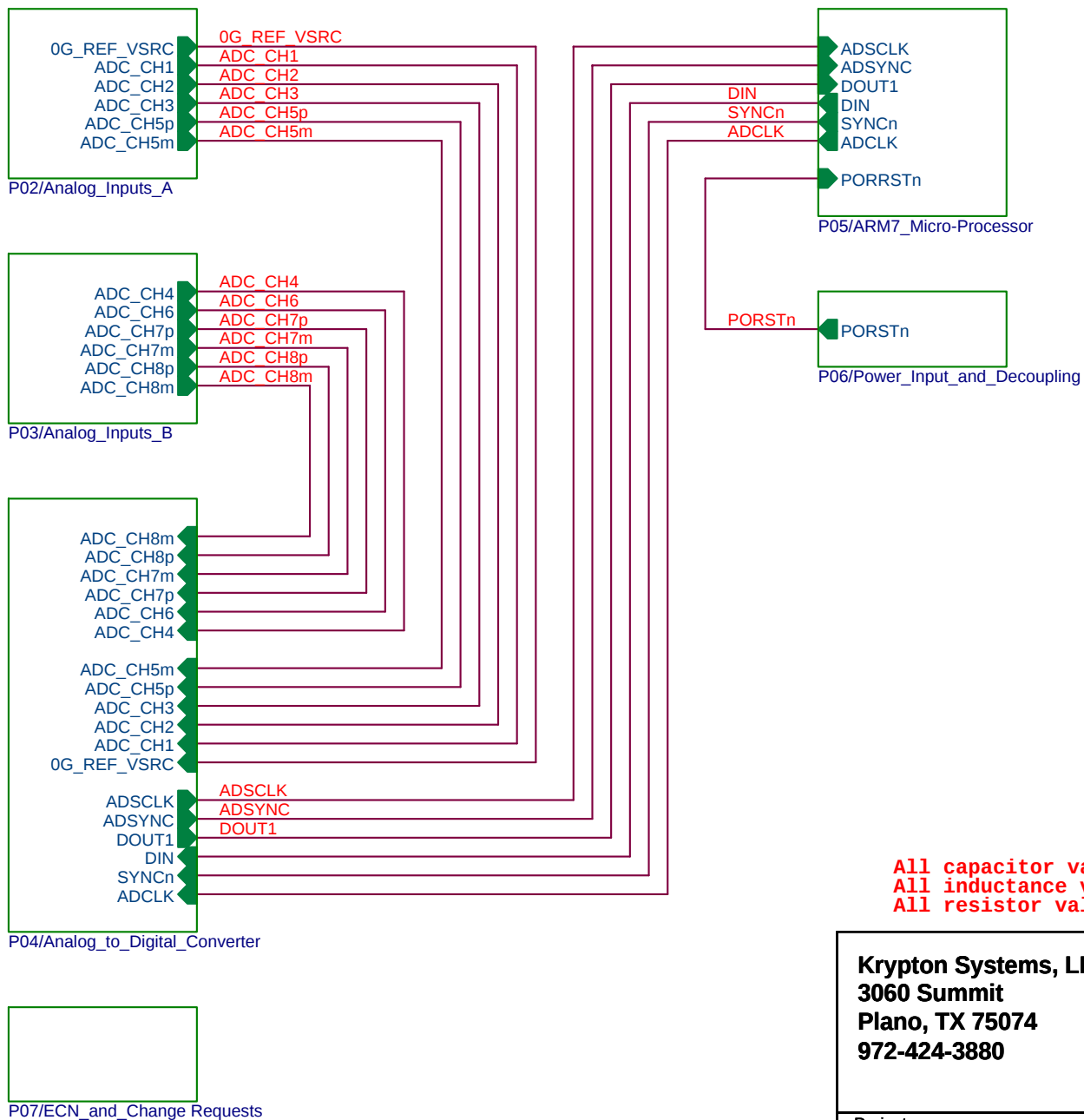


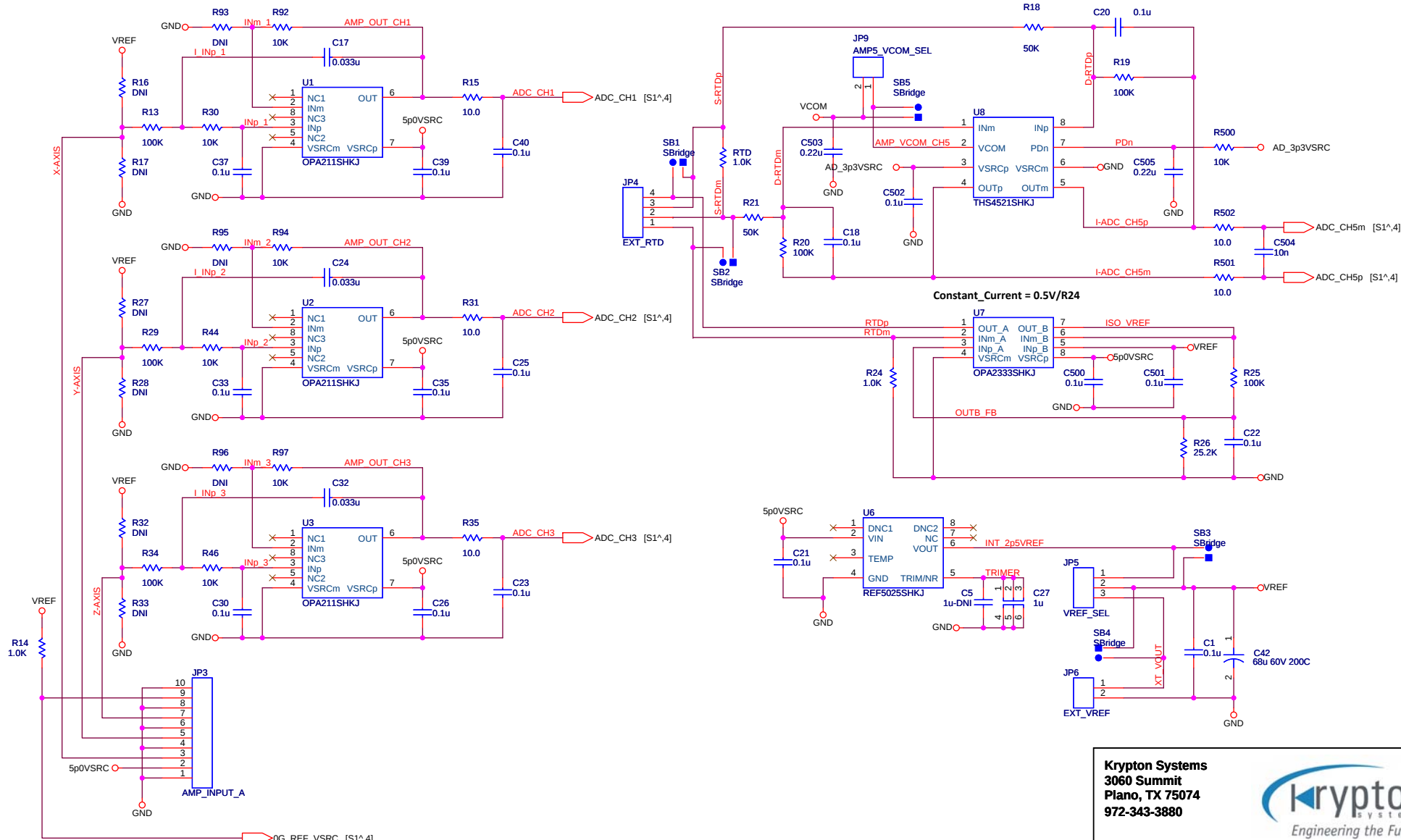


All capacitor values are shown as farads.
 All inductance values are shown as henries.
 All resistor values are shown as ohms.

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Project TI HEAT EVM Rev-B			
Size A	Eng KWH	Drawing File Name Hiearchical_Block_Diagram	Rev B
Date: Friday, May 18, 2012		Sheet 1	of 7

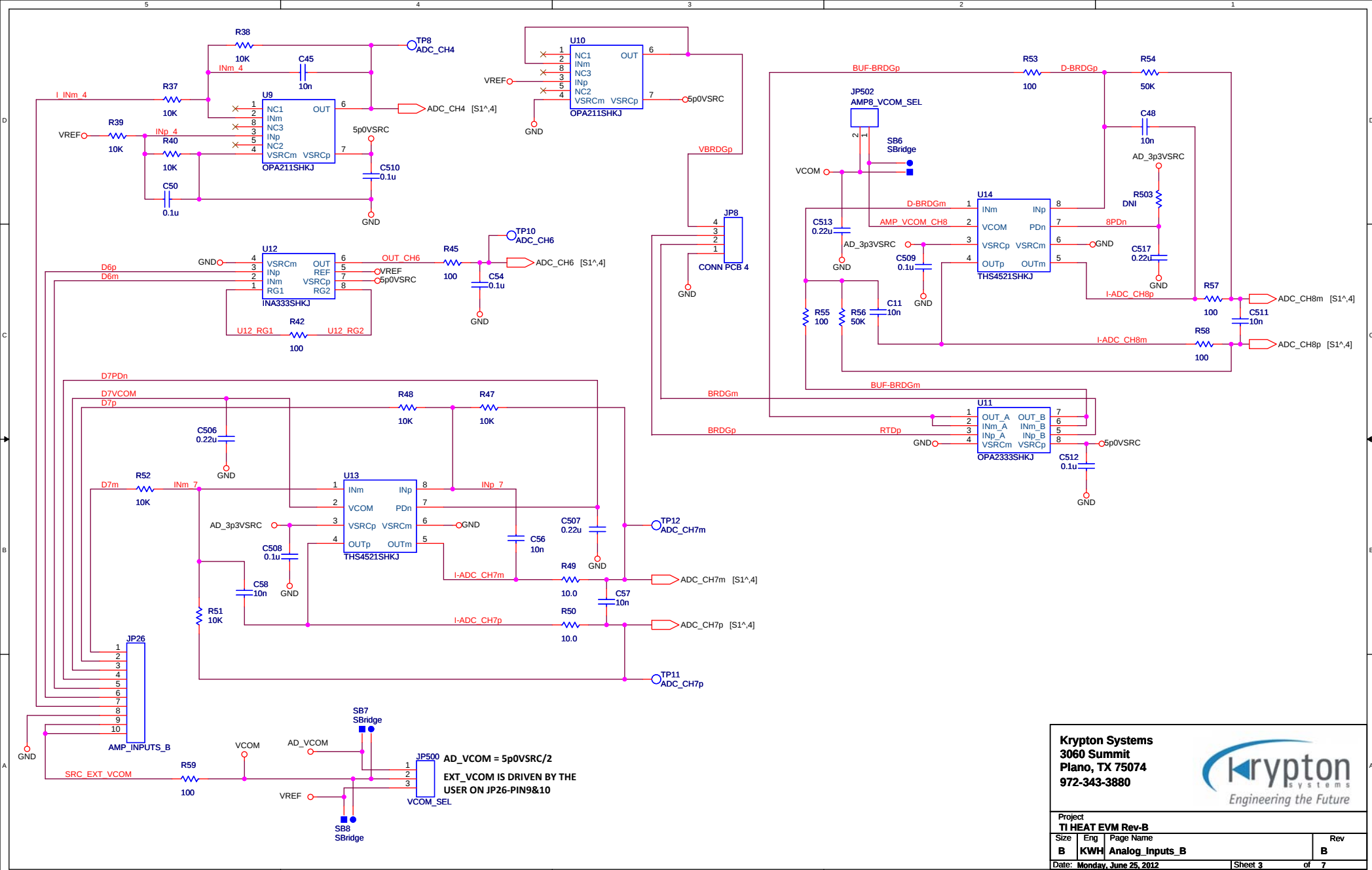


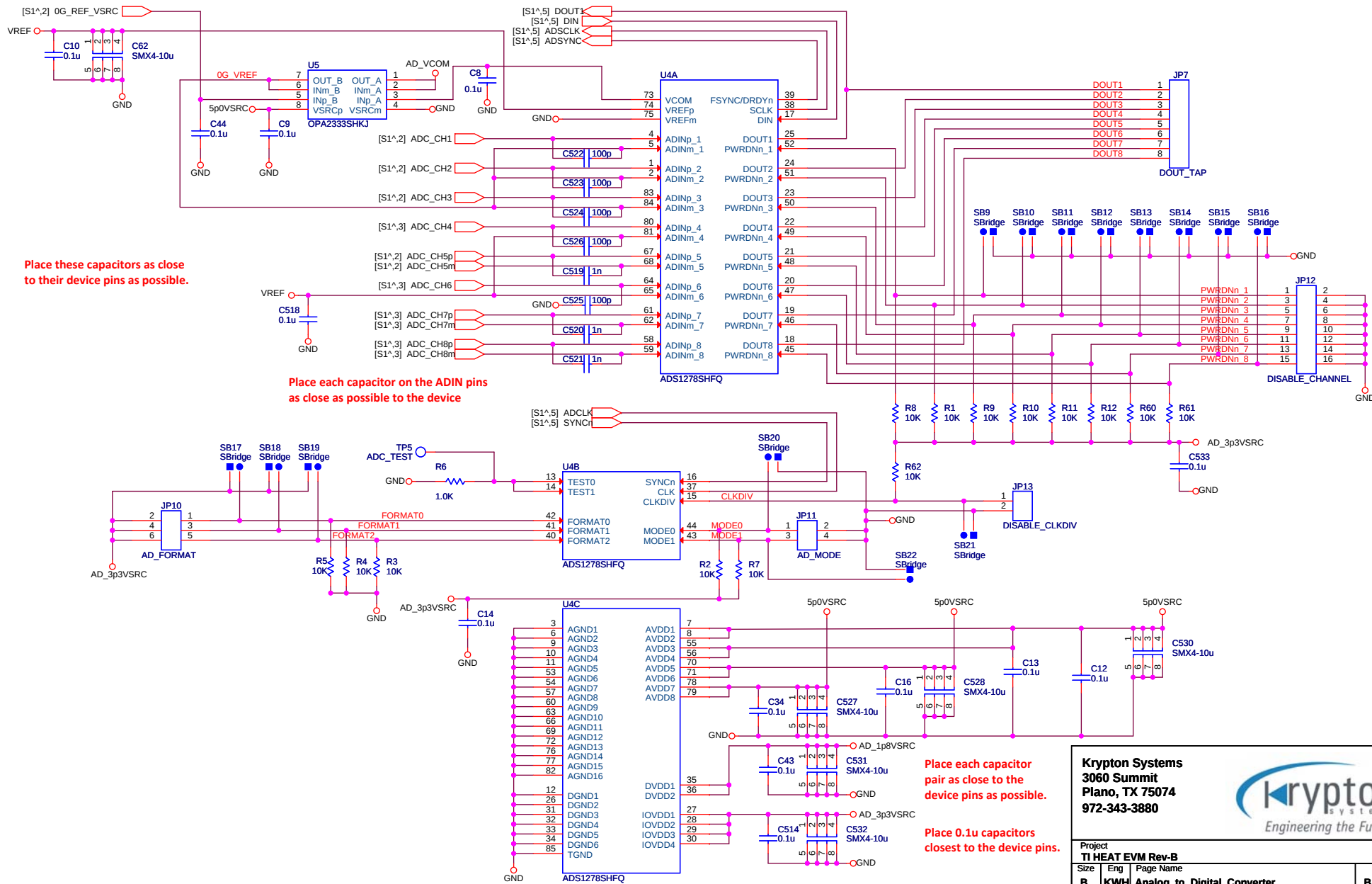
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Project			
TI HEAT EVM Rev-B			
Size	Eng	Page Name	
B	KWH	Analog_Inputs_A	
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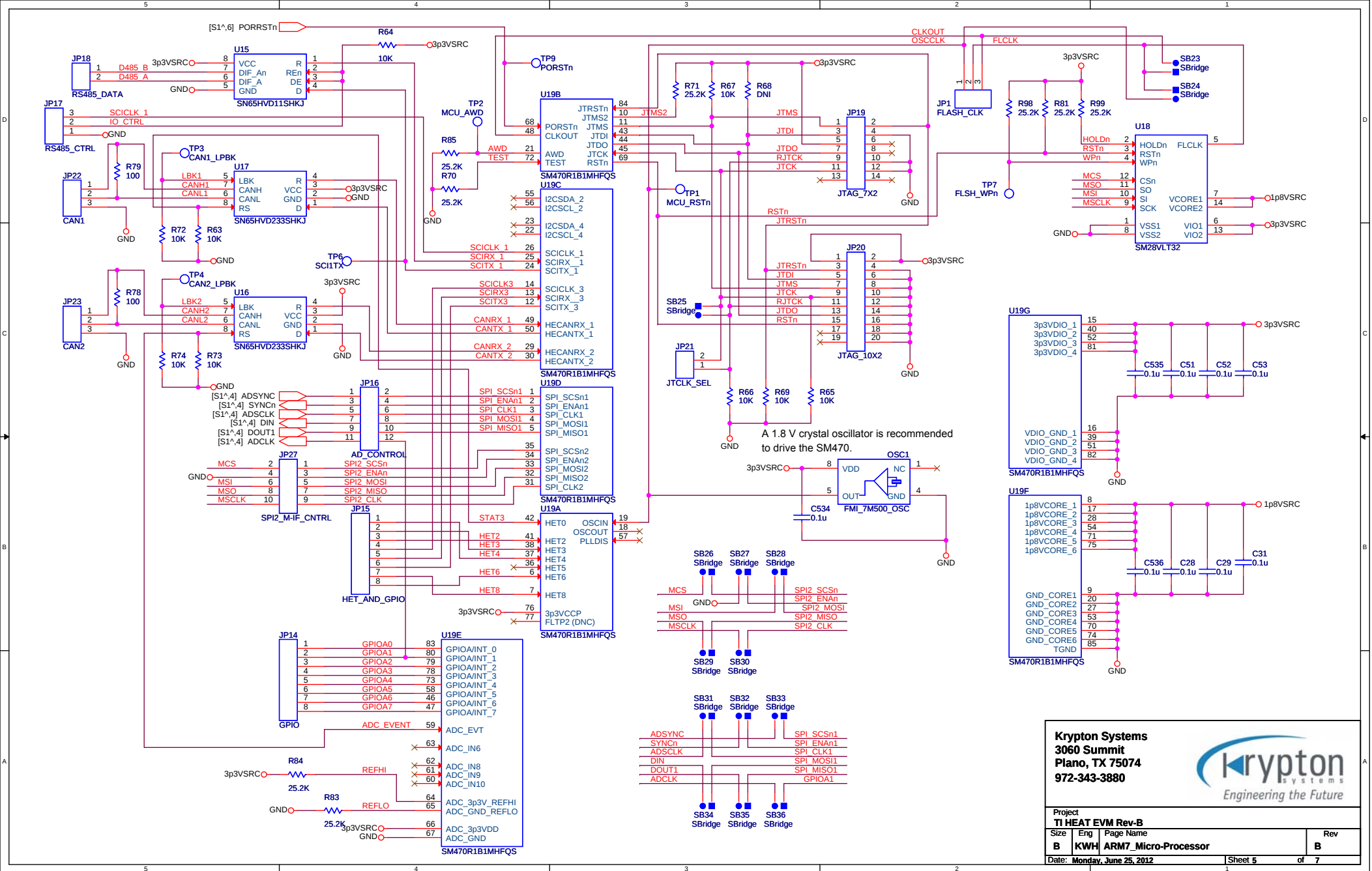
krypton
 Engineering the Future

Project
TI HEAT EVM Rev-B

Size Eng Page Name Rev

B KWH Analog_to_Digital_Converter B

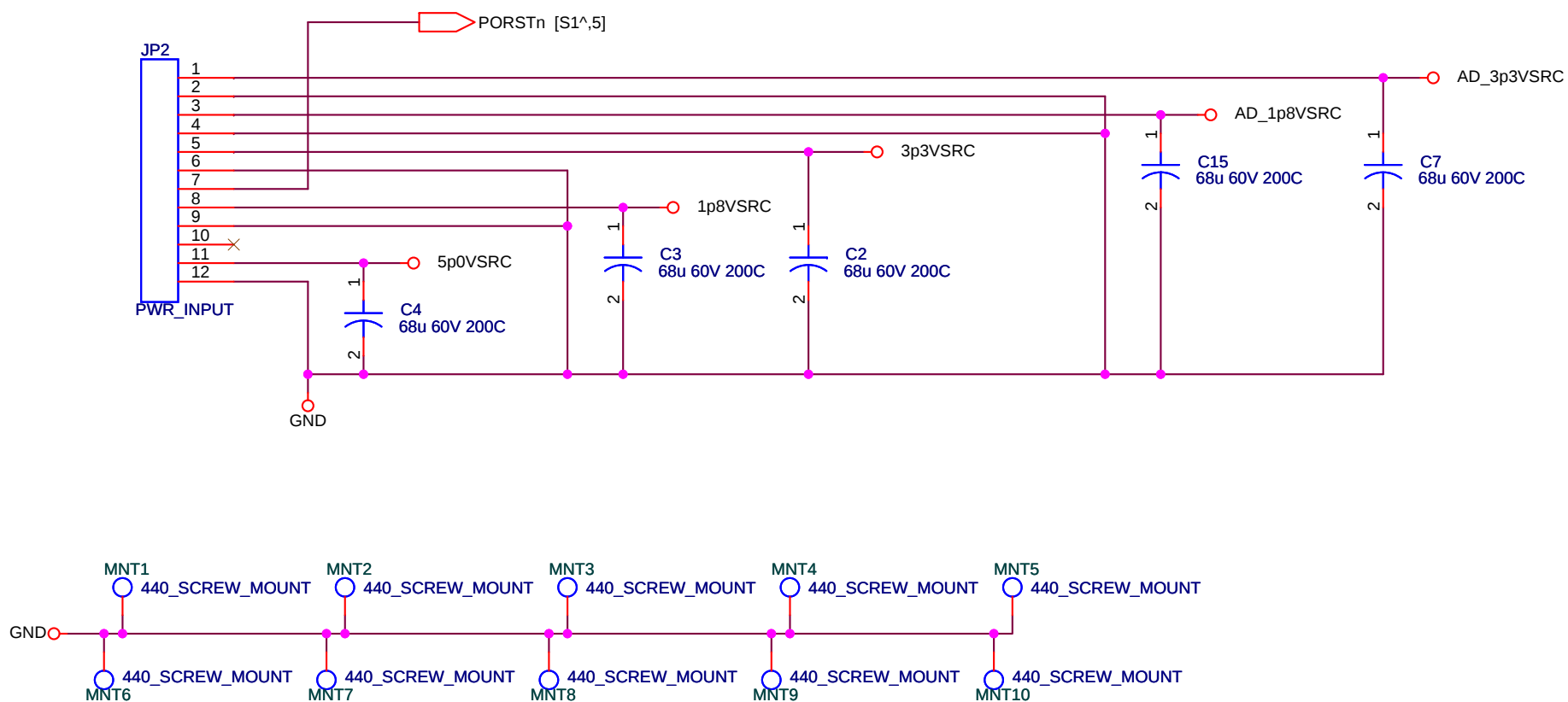
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Project TI HEAT EVM Rev-B			
Size B	Eng KWH	Page Name ARM7_Micro-Processor	Rev B
Date: Monday, June 25, 2012		Sheet 5 of 7	



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Project TI HEAT EVM Rev-B			
Size A	Eng KWH	Page Name Power_Input_and_Decoupling	Rev B
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TI_HEATEVM_REV-M_010312.DSN

FOLLOWING SCHEMATIC AND LAYER PLACEMENT REVIEW WE MODIFIED THE POWER INPUT STRUCTURES, CHANGED Y-AXIS AND Z-AXIS FILTERS SO THAT THEY EQUAL THE X-AXIS FILTERS. THE ITEMS IN REV-H, REV-J, AND REV-K WERE APPROVED.

BOARD WAS RELEASED TO LAYOUT. LAYOUT REVIEW WILL BE HELD WHEN PLACEMENT IS FINALIZED.

KWH

01/18/12

TI_HEATEVM_REV-N_010312.DSN

MODIFIED SCHEMATIC TO REFLECT THE ERRORS NOTED DURING LAYOUT

KWH

01/23/12

- 1) SB27 HAS AN OPEN PIN
- 2) SB7 AND SB8 ARE CONNECTED TO THE SAME NET. SB8 WAS MOVED TO CORRECT NET
- 3) BOARD GREW 0.4 INCH LONGER AND NEEDED TWO MORE MOUNTING HOLES
- 4) ADDED C535 AND C536 TO ARM7 SO THAT EACH SIDE OF THE DEVICE HAS A DECOUPLING CAP ON BOTH POWER NETS

TI_HEATEVM_REV-P_010312.DSN

ADDED FOOTPRINT TO JP2

KWH

01/23/12

TI_HEATEVM_REV-S_010312.DSN

THE REFHI NET WAS BROKEN, IT WAS CONNECTED AT R84.

KWH

01/27/12

TI_HEATEVM_REV-T_010312.DSN

SOME COMPONENT VALUES WERE UPDATED PER THE NEW DESIGN RULES FROM TI. SOME PART NUMBERS AND/OR FOOTPRINTS WERE UPDATED TO BRING BOM IN STEP WITH THE OLD BOM>

KWH

02/01/12

TI_HEATEVM_REV_A1_030912.DSN

REVIEW WITH HECTOR TORRES. SCHEMATIC EDITED BASED ON HECTORS FEEDBACK. A/D CONNECTIONS TO 0G NET, VCOM AND VREF NETS WERE MODIFIED

NIMA

03/09/12

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Project

TI HEAT EVM Rev-B

Size

Eng

Page Name

Rev

A

KWH

ECN_and_Change Requests

B

Date: **Friday, May 18, 2012**

Sheet **7**

of **7**

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